

## Technical University Hamburg-Harburg

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- [TUHH-14] T. Baras, J. Müller and A. F. Jacob, „**K-Band LTCC Star Mixer with Broadband IF Output Network**“, IEEE International Microwave Symposium (IMS), Honolulu, Hawaii, USA, June 2007
- [TUHH-15] T. Baras, M. Corrales Hernandez, A. F. Jacob, „**Electrical and Thermo-mechanical Evaluation of 2<sup>nd</sup>-Level-Interconnects for LTCC modules**“, Intl. Microelectronics and Packaging Symposium (IMAPS) 2006, San Diego, USA, October 2006
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